

## HMC389LP4 / 389LP4E

v03.0507

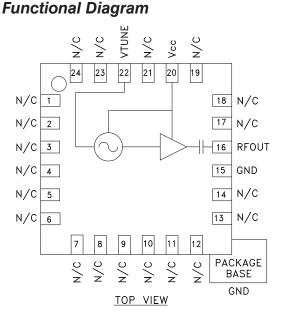


MMIC VCO w/ BUFFER AMPLIFIER, 3.35 - 3.55 GHz

#### Typical Applications

Low noise MMIC VCO w/Buffer Amplifier for:

- Wireless Local Loop (WLL)
- VSAT & Microwave Radio
- Test Equipment & Industrial Controls
- Military



#### **Features**

Pout: +4.7 dBm

Phase Noise: -112 dBc/Hz @100 KHz

No External Resonator Needed

Single Supply: 3V @ 41 mA

QFN Leadless SMT Package, 16 mm<sup>2</sup>

#### **General Description**

The HMC389LP4 & HMC389LP4E are GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCOs with integrated resonators, negative resistance devices, varactor diodes, and buffer amplifiers. Covering 3.35 to 3.55 GHz, the VCO's phase noise performance is excellent over temperature, shock, vibration and process due to the oscillator's monolithic structure. Power output is 4.7 dBm typical from a single supply of 3V @ 41mA. The voltage controlled oscillator is packaged in a low cost leadless QFN 4x4 mm surface mount package.

## Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc = +3V

Parameter	Min.	Тур.	Max.	Units
Frequency Range	3.35 - 3.55		GHz	
Power Output	1.5	4.7		dBm
SSB Phase Noise @ 100 kHz Offset, Vtune= +5V @ RF Output		-112		dBc/Hz
Tune Voltage (Vtune)	0		10	V
Supply Current (Icc) (Vcc = +3.0V)		41		mA
Tune Port Leakage Current			10	μΑ
Output Return Loss		6		dB
Harmonics 2nd 3rd		-7 -16		dBc dBc
Pulling (into a 2.0:1 VSWR)		3.3		MHz pp
Pushing @ Vtune= +5V		-3		MHz/V
Frequency Drift Rate		0.4		MHz/°C

## **HMC389\* PRODUCT PAGE QUICK LINKS**

Last Content Update: 02/23/2017

## COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

## **EVALUATION KITS**

• HMC389LP4 Evaluation Board

### **DOCUMENTATION**

#### **Application Notes**

 Determining the FM Bandwidth of a Wideband Varactor Tuned VCO

#### **Data Sheet**

· HMC389 Data Sheet

## REFERENCE MATERIALS 🖳

#### **Quality Documentation**

- Package/Assembly Qualification Test Report: LP4, LP4B, LP4C, LP4K (QTR: 2013-00487 REV: 04)
- Package/Assembly Qualification Test Report: Plastic Encapsulated QFN (QTR: 05006 REV: 02)
- Semiconductor Qualification Test Report: GaAs HBT-A (OTR: 2013-00228)

## **DESIGN RESOURCES**

- HMC389 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

#### **DISCUSSIONS**

View all HMC389 EngineerZone Discussions.

### SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

## **TECHNICAL SUPPORT**

Submit a technical question or find your regional support number.

#### DOCUMENT FEEDBACK $\Box$

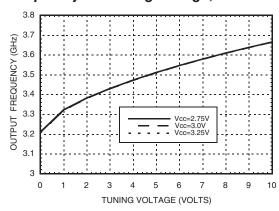
Submit feedback for this data sheet.



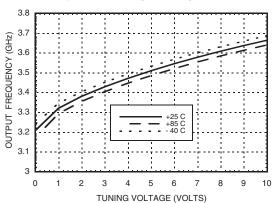


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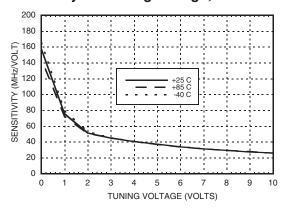
#### Frequency vs. Tuning Voltage, T= 25°C



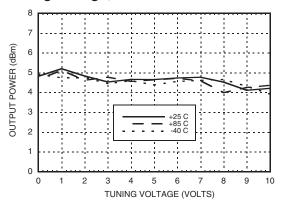
#### Frequency vs. Tuning Voltage, Vcc= +3V



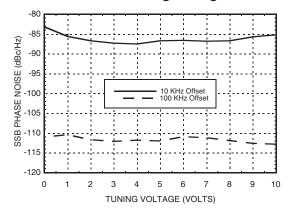
#### Sensitivity vs. Tuning Voltage, Vcc= +3V



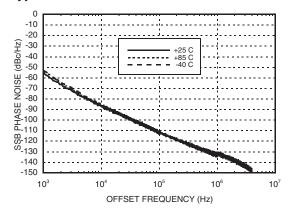
Output Power vs.
Tuning Voltage, Vcc= +3V



#### Phase Noise vs. Tuning Voltage



#### Typical SSB Phase Noise @ Vtune= +5V







## MMIC VCO w/ BUFFER AMPLIFIER, 3.35 - 3.55 GHz

#### **Absolute Maximum Ratings**

Vcc	+3.5 Vdc
Vtune	0 to +11V
Channel Temperature	135 °C
Continuous Pdiss (T = 85°C) (derate 6.28 mW/°C above 85°C)	565 W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

#### Typical Supply Current vs. Vcc

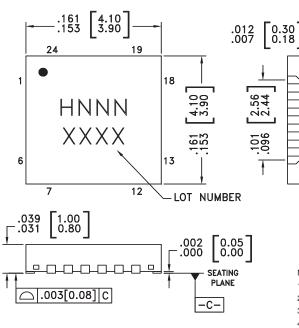
Vcc (V)	Icc (mA)	
2.75	35	
3.0	41	
3.25	46	

Note: VCO will operate over full voltage range shown above.

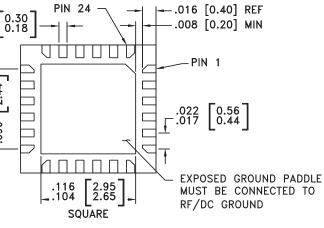


ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

#### **Outline Drawing**



#### **BOTTOM VIEW**



#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
  PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOT FOR SUGGESTED LAND PATTERN.

#### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC389LP4	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H389 XXXX
HMC389LP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H389 XXXX

- [1] Max peak reflow temperature of 235  $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX





# MMIC VCO w/ BUFFER AMPLIFIER, 3.35 - 3.55 GHz

#### **Pin Descriptions**

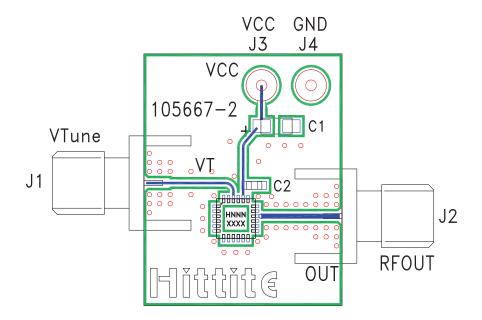
Pin Number	Function	Description	Interface Schematic
1- 14, 17 - 19, 21, 23, 24	N/C	No Connection	
15	GND	This pin must be connected to RF & DC ground.	GND =
16	RFOUT	RF output (AC coupled)	—   —○ RFOUT
20	Vcc	Supply Voltage Vcc= 3V	Vcc O26pF
22	VTUNE	Control Voltage Input. Modulation port bandwidth dependent on drive source impedance.	7.5nH 1500 VTUNEO C;= 10pF
	GND	Package bottom has an exposed metal paddle that must be RF & DC grounded.	○ GND =





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#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 105706 [1]

Item	Description	
J1 - J2	PCB Mount SMA RF Connector	
J3 - J4	DC Pin	
C1	4.7 μF Tantalum Capacitor	
C2	10,000 pF Capacitor, 0603 Pkg.	
U1	HMC389LP4 / HMC389LP4E VCO	
PCB [2]	105667 Eval Board	

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350



v02.0805



Notes:

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